

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A conductive composition comprising a ~~particulate-silver containing component compound~~ and a binder, wherein when said silver containing component comprises a particulate silver compound and the quantity of said binder used relative to 100 parts by weight of said ~~particulate-silver containing component compound~~ is within a range of from 0.78 to 2.36 parts by weight.

2. (currently amended): A conductive composition comprising a ~~particulate-silver containing component compound~~, a reducing agent and a binder, wherein said silver containing component comprises a particulate silver compound and the quantity of said binder used relative to 100 parts by weight of said ~~particulate-silver containing component compound~~ is within a range of from 0.78 to 2.36 parts by weight.

3. (previously presented): The conductive composition according to either claim 1 or claim 2, wherein said particulate silver compound is one or more of silver oxide, silver carbonate and silver acetate.

4. (previously presented): The conductive composition according to either claim 1 or claim 2, wherein an average particle diameter of said particulate silver compound is within a range from 0.01 to 10 μm .

5. (previously presented): The conductive composition according to either claim 1 or claim 2, wherein said binder is one or more materials selected from a group consisting of polyvalent phenol compounds, phenol resins, alkyd resins, polyester resins and epoxy resins.

6. (previously presented): The conductive composition according to either claim 1 or claim 2, wherein said binder exhibits a reducing action.

7. (previously presented): The conductive composition according to either claim 1 or claim 2, wherein said binder is a fine powder of a thermoplastic resin with an average particle diameter within a range from 20 nm to 5 μm .

8. (previously presented): The conductive composition according to claim 7, wherein said thermoplastic resin is polystyrene or polyethylene terephthalate.

9. (previously presented): The conductive composition according to claim 2, wherein said reducing agent is one or more of ethylene glycol, diethylene glycol, triethylene glycol and ethylene glycol diacetate.

10. (previously presented): The conductive composition according to either claim 1 or claim 2, having a viscosity within a range from 30 to 300 dPa·sec.

11. (previously presented): A method of forming a conductive coating comprising the steps of applying and then heating a conductive composition according to either claim 1 or claim 2.

12. (previously presented): The method of forming a conductive coating according to claim 11 wherein a heating temperature is within a range from 140 to 200°C.

13. (previously presented): A conductive coating, produced by a formation method according to claim 11, wherein silver particles are fused together.

14. (previously presented): The conductive coating according to claim 13, having a volume resistivity of $3.0 \times 10^{-5} \Omega\cdot\text{cm}$ or less.

15. (previously presented): The conductive composition according to claim 3, wherein said particulate silver compound is one or more of silver oxide and silver carbonate.